MA2YD15

Silicon epitaxial planar type

For high frequency rectification

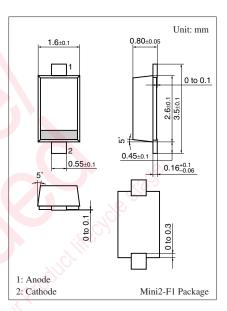
■ Features

- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage V_F
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	20	V
Repetitive peak reverse voltage	V _{RRM}	25	V
Forward current (Average) *1	I _{F(AV)}	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *1: Mounted on an alumina PC board



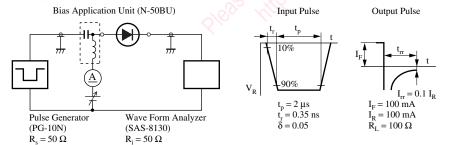
Marking Symbol: 2R

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

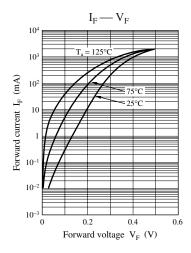
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 1.0 \text{ A}$	000	OUI.	0.45	V
Reverse current	I_R	$V_R = 20 \text{ V}$	6		100	μΑ
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$	100 J	120		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$	7.7	10		ns
	1	$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

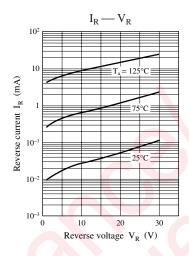
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

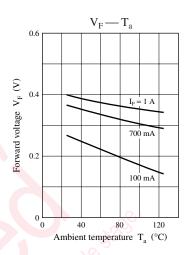
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. *: t_{rr} measurement circuit

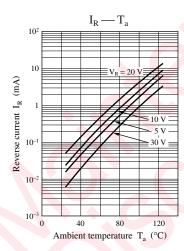


^{*2:} The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)









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